









Release Date: 16 April 2023 Version: A1.0

# PRODUCT DATASHEET



- ► PTH/THT Lamp
- ➤ 3mm Round 5.3t
- ► Phototransistor (PT) for matching NOF00L29

N0P08L56 (Bulk) NOPO8L56T (Tape)





# 3mm Round Lamp compliant





#### **FEATURES:**

NOPO8L56 consist of NPN silicon phototransistor mounted in clear lens, is mechanically and spectrally matched to infrared emitting diode N0F00L29 or similar.

- Package: PTH/THT LED Lamp 3mm Round 5.3t
- Wavelength of Max. Sensitivity (typ.): 900nm
- Receiving Angle: 30°
- **Materials:** 
  - Die: Silicon
  - Resin: Epoxy (Water Clear)
- Operating Temperature: -40~+85°C
- Storage Temperature: -50~+100°C
- Soldering methods: Hand; Soldering Heat (DIP)
- MSL Level: acc. to JEDEC Level 3
- Packing: 500pcs/bulk; 2000pcs/tape (Ammo Pack)

#### **APPLICATIONS:**

- Remote Control
- **Automatic Control System**
- Burglar Alarm
- **Photo Detector**
- Smoke
- Detector
- Computer I/O Peripheral
- Industrial Use



## **CHARACTERISTICS:**

# Absolute Maximum Characteristics (Ta=25°C)

| Parameter                            | Symbol            | Ratings  | Unit |
|--------------------------------------|-------------------|----------|------|
| Emitter-Collector Breakdown Voltage  | BV <sub>ECO</sub> | 5        | V    |
| Collector-Emitter Sustaining Voltage | V <sub>CE</sub>   | 30       | V    |
| Power Dissipation                    | P <sub>D</sub>    | 100      | mW   |
| Operating Temperature                | T <sub>OPR</sub>  | -40~+85  | °C   |
| Storage Temperature                  | T <sub>STG</sub>  | -50~+100 | °C   |
| Relative Humidity at 85°C            | hr                | 85       | %    |

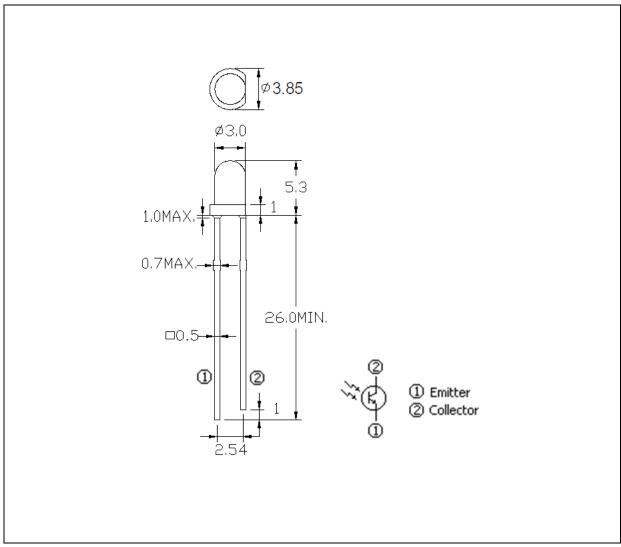
# Electrical & Optical Characteristics (Ta=25°C)

| Parameter                              | Symbol                | Values |      |      | l loit | Test Condition  |
|--|-----------------------|--------|------|------|--------|---|
| Parameter                              | Symbol                | Min.   | Тур. | Max. | Unit   | rest Condition  |
| Collector-Emitter Sustaining Voltage   | V <sub>CE</sub>       | 30     | 60   |      | V      | I <sub>c</sub> =0.5mA<br>Ee=0mW/cm²                       |
| Collector-Emitter Saturation Voltage   | V <sub>CE</sub> (SAT) |        | 0.4  |      | V      | I <sub>c</sub> =100μA<br>Ee=0.6mW/cm²                     |
| Emitter-Collector<br>Breakdown Voltage | BV <sub>ECO</sub>     | 5      | 7    |      | V      | l <sub>e</sub> =100μA<br>Ee=0mW/cm²                       |
| Dark Current                           | I <sub>D</sub>        |        |      | 100  | nA     | V <sub>CE</sub> =10V<br>Ee=0mW/cm <sup>2</sup>            |
| Photo Current                          | Iι                    | 1      | 4    |      | mA     | V <sub>CE</sub> =5V<br>Ee=1.0mW/cm <sup>2</sup>           |
| Rise Time (10% to 90%)                 | T <sub>R</sub>        |        | 10   |      | μS     | V <sub>cc</sub> =5V<br>I <sub>L</sub> =800μA<br>RL=1K OHM |
| Fall Time (90% to 10%)                 | T <sub>F</sub>        |        | 15   |      | μS     |   |



## **OUTLINE DIMENSION:**

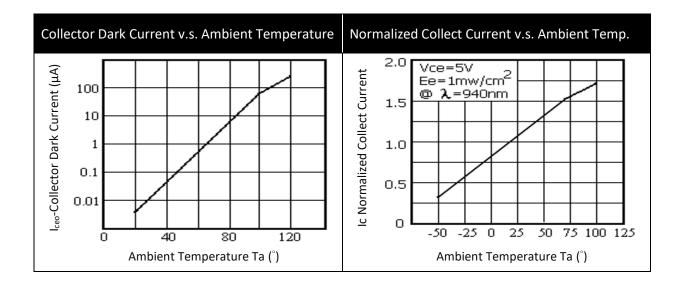
## Package Dimension:

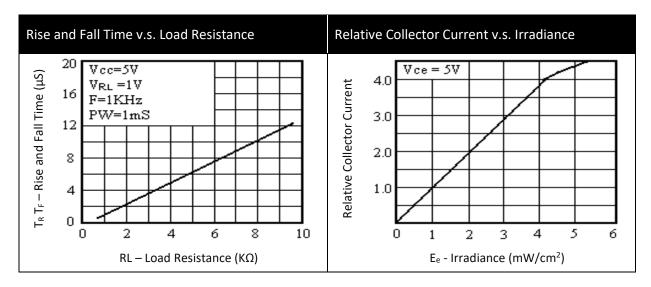


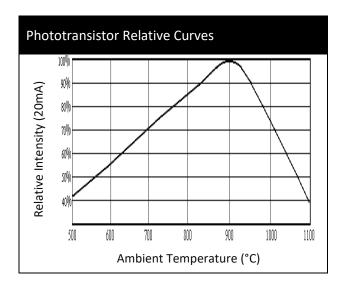
- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.2mm, unless otherwise noted.



### **ELECTRO-OPTICAL CHARACTERISTICS:**







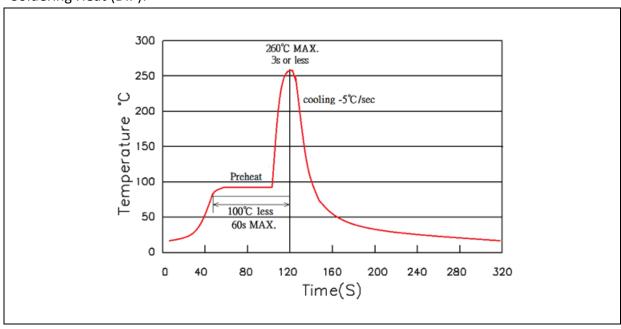


### **RECOMMENDED SOLDERING PROFILE:**

## Hand Solder (Solder Iron):

- Temperature at tip of iron: 350°C Max.
- Soldering Time: 3 seconds ± 1 sec.

## Soldering Heat (DIP):



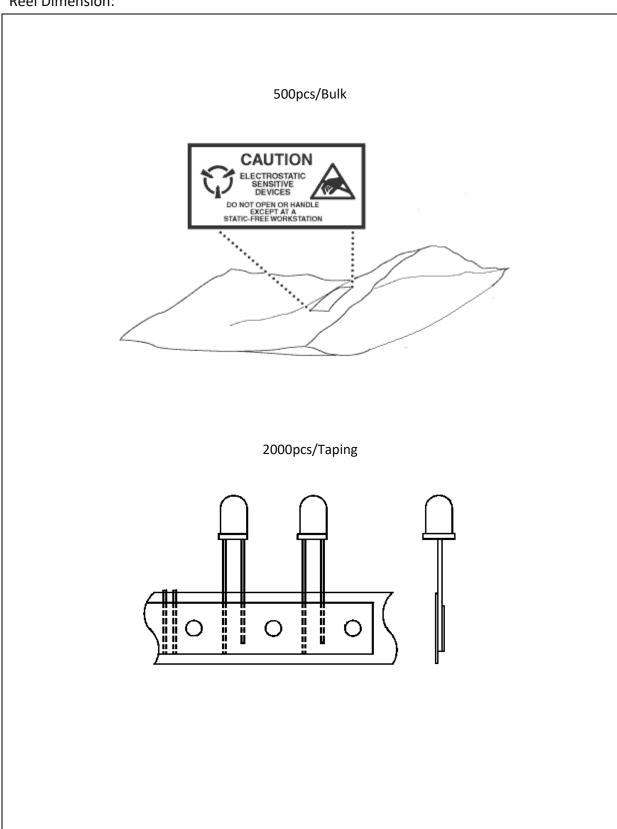
#### Note:

- 1. Maximum reflow soldering: 1 time.
- 2. Before, during, and after soldering, should not apply stress on the components and PCB board.



## **PACKING SPECIFICATION:**

### Reel Dimension:





#### **PRECAUTIONS OF USE:**

#### Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent <10% R.H. and apply baking before use.

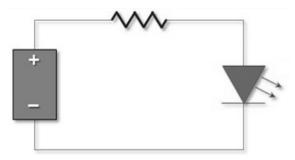
#### Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

• 60±5°C x 24hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

## **Testing Circuit:**



Must apply resistor(s) for protection (over current proof).

### Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

## ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.



# **REVISION RECORD:**

| Version | Date       | Summary of Revision |
|---------|------------|---------------------|
| A1.0    | 16/04/2023 | Datasheet set-up.   |